

(19) World Intellectual Property
Organization
International Bureau



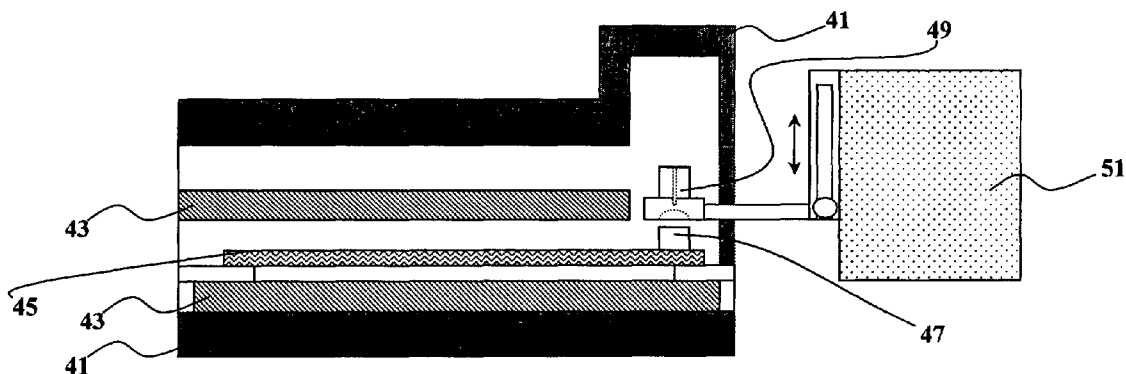
(43) International Publication Date
21 May 2004 (21.05.2004)

PCT

(10) International Publication Number
WO 2004/042764 A2

- (51) International Patent Classification⁷: **H01J 9/00** (72) Inventors: **COOPER, Timothy, J.**; 3433 County Route 2, Addison, NY 14801 (US). **SHAH, Kashyap, H.**; 114 FieldView Drive, Painted Post, NY 14870 (US).
- (21) International Application Number: PCT/US2003/033494 (74) Agent: **BEALL, Thomas, R.**; Corning Incorporated, SP TI 3 1, Corning, NY 14831 (US).
- (22) International Filing Date: 21 October 2003 (21.10.2003)
- (25) Filing Language: English (81) Designated States (*national*): CN, JP, KR, SG.
- (26) Publication Language: English Published:
— without international search report and to be republished upon receipt of that report
- (30) Priority Data:
10/284,589 31 October 2002 (31.10.2002) US
- (71) Applicant: **CORNING INCORPORATED** [US/US]; 1 Riverfront Plaza, Corning, NY 14831 (US).
For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: SEALING LIGHTING DEVICE COMPONENT ASSEMBLY WITH SOLDER GLASS PREFORM BY USING INDUCTION HEATING



(57) Abstract: Disclosed is a process for sealing component assembly to an electrical lighting device using induction heating. The assembly comprises the component, such as an electrode lead wire, and a solder glass preform. The process is useful, for example, in hermetically sealing and affixing lamp components, such as electrical lead wires and exhaust tubulation, to a low-pressure fluorescent discharge lamp envelope having phosphor coating already applied thereto. The present invention is particularly suitable for lamp envelopes made of borosilicate glass having a CTE from 0 to 300°C in the range of 30-45x10⁻⁷ °C⁻¹.

WO 2004/042764 A2